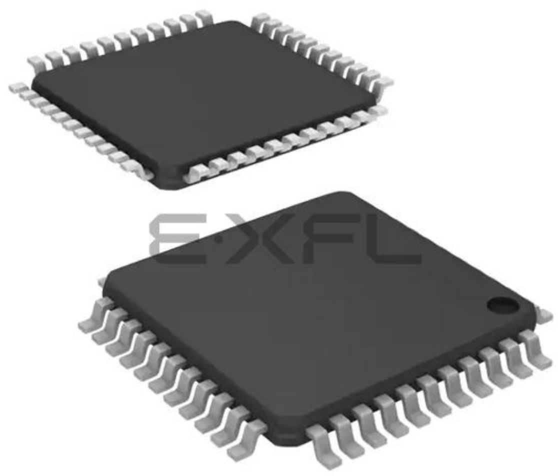

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 14x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32mc104t-e-pt

3.6.1 MULTIPLIER

The 17-bit x 17-bit multiplier is capable of signed or unsigned operation and can multiplex its output using a scaler to support either 1.31 fractional (Q31) or 32-bit integer results. Unsigned operands are zero-extended into the 17th bit of the multiplier input value. Signed operands are sign-extended into the 17th bit of the multiplier input value. The output of the 17-bit x 17-bit multiplier/scaler is a 33-bit value that is sign-extended to 40 bits. Integer data is inherently represented as a signed 2's complement value, where the Most Significant bit (MSb) is defined as a sign bit. The range of an N-bit 2's complement integer is -2^{N-1} to $2^{N-1} - 1$.

- For a 16-bit integer, the data range is -32768 (0x8000) to 32767 (0x7FFF) including 0.
- For a 32-bit integer, the data range is -2,147,483,648 (0x8000 0000) to 2,147,483,647 (0x7FFF FFFF).

When the multiplier is configured for fractional multiplication, the data is represented as a 2's complement fraction, where the MSb is defined as a sign bit and the radix point is implied to lie just after the sign bit (QX format). The range of an N-bit 2's complement fraction with this implied radix point is -1.0 to $(1 - 2^{1-N})$. For a 16-bit fraction, the Q15 data range is -1.0 (0x8000) to 0.999969482 (0x7FFF) including 0 and has a precision of 3.01518×10^{-5}. In Fractional mode, the 16 x 16 multiply operation generates a 1.31 product that has a precision of 4.65661×10^{-10}.

The same multiplier is used to support the MCU multiply instructions, which include integer 16-bit signed, unsigned and mixed sign multiply operations.

The `MUL` instruction can be directed to use byte or word-sized operands. Byte operands will direct a 16-bit result and word operands will direct a 32-bit result to the specified register(s) in the W array.

3.6.2 DATA ACCUMULATORS AND ADDER/SUBTRACTER

The data accumulator consists of a 40-bit adder/subtracter with automatic sign extension logic. It can select one of two accumulators (A or B) as its pre-accumulation source and post-accumulation destination. For the `ADD` and `LAC` instructions, the data to be accumulated or loaded can be optionally scaled using the barrel shifter prior to accumulation.

3.6.2.1 Adder/Subtracter, Overflow and Saturation

The adder/subtracter is a 40-bit adder with an optional zero input into one side and either true or complement data into the other input.

- In the case of addition, the Carry/$\overline{\text{Borrow}}$ input is active-high and the other input is true data (not complemented).
- In the case of subtraction, the Carry/$\overline{\text{Borrow}}$ input is active-low and the other input is complemented.

The adder/subtracter generates Overflow Status bits, SA/SB and OA/OB, which are latched and reflected in the STATUS Register:

- Overflow from bit 39: this is a catastrophic overflow in which the sign of the accumulator is destroyed.
- Overflow into guard bits 32 through 39: this is a recoverable overflow. This bit is set whenever all the guard bits are not identical to each other.

The adder has an additional saturation block that controls accumulator data saturation, if selected. It uses the result of the adder, the Overflow Status bits described previously, and the SAT<A:B> (CORCON<7:6>) and ACCSAT (CORCON<4>) mode control bits to determine when and to what value, to saturate.

Six STATUS Register bits support saturation and overflow:

- OA: ACCA overflowed into guard bits
- OB: ACCB overflowed into guard bits
- SA: ACCA saturated (bit 31 overflow and saturation)

  or

  ACCA overflowed into guard bits and saturated (bit 39 overflow and saturation)
- SB: ACCB saturated (bit 31 overflow and saturation)

  or

  ACCB overflowed into guard bits and saturated (bit 39 overflow and saturation)
- OAB: Logical OR of OA and OB
- SAB: Logical OR of SA and SB

The OA and OB bits are modified each time data passes through the adder/subtracter. When set, they indicate that the most recent operation has overflowed into the accumulator guard bits (bits 32 through 39). The OA and OB bits can also optionally generate an arithmetic warning trap when OA and OB are set and the corresponding Overflow Trap Flag Enable bits (OVATE, OVBTE) in the INTCON1 register are set (refer to **Section 7.0 "Interrupt Controller"**). This allows the user application to take immediate action; for example, to correct system gain.

4.2.6 SOFTWARE STACK

In addition to its use as a working register, the W15 register in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices is also used as a Software Stack Pointer. The Stack Pointer always points to the first available free word and grows from lower to higher addresses. It pre-decrements for stack pops and post-increments for stack pushes, as shown in Figure 4-6. For a PC push during any `CALL` instruction, the MSb of the PC is zero-extended before the push, ensuring that the MSb is always clear.

> **Note:** A PC push during exception processing concatenates the SRL register to the MSb of the PC prior to the push.

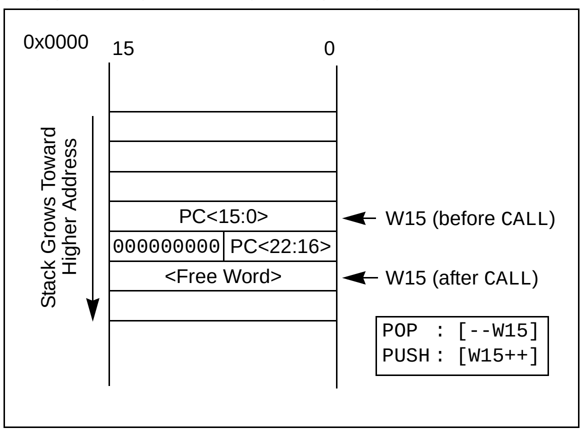
The Stack Pointer Limit register (SPLIM) associated with the Stack Pointer sets an upper address boundary for the stack. SPLIM is uninitialized at Reset. As is the case for the Stack Pointer, SPLIM<0> is forced to '`0`' because all stack operations must be word-aligned.

Whenever an EA is generated using W15 as a source or destination pointer, the resulting address is compared with the value in SPLIM. If the contents of the Stack Pointer (W15) and the SPLIM register are equal and a push operation is performed, a stack error trap will not occur. However, the stack error trap will occur on a subsequent push operation. For example, to cause a stack error trap when the stack grows beyond address 0x0C00 in RAM, initialize the SPLIM with the value 0x0BFE.

Similarly, a Stack Pointer underflow (stack error) trap is generated when the Stack Pointer address is found to be less than 0x0800. This prevents the stack from interfering with the SFR space.

A write to the SPLIM register should not be immediately followed by an indirect read operation using W15.

FIGURE 4-6: CALL STACK FRAME



4.2.7 DATA RAM PROTECTION FEATURE

The dsPIC33F product family supports data RAM protection features that enable segments of RAM to be protected when used in conjunction with Boot and Secure Code Segment Security. BSRAM (Secure RAM Segment for BS) is accessible only from the Boot Segment Flash code when enabled. SSRAM (Secure RAM Segment for RAM) is accessible only from the Secure Segment Flash code when enabled. See Table 4-1 for an overview of the BSRAM and SSRAM SFRs.

4.3 Instruction Addressing Modes

The addressing modes shown in Table 4-40 form the basis of the addressing modes that are optimized to support the specific features of individual instructions. The addressing modes provided in the `MAC` class of instructions differ from those provided in other instruction types.

4.3.1 FILE REGISTER INSTRUCTIONS

Most file register instructions use a 13-bit address field (f) to directly address data present in the first 8192 bytes of data memory (Near Data Space). Most file register instructions employ a Working register, W0, which is denoted as WREG in these instructions. The destination is typically either the same file register or WREG (with the exception of the `MUL` instruction), which writes the result to a register or register pair. The `MOV` instruction allows additional flexibility and can access the entire data space.

4.3.2 MCU INSTRUCTIONS

The three-operand MCU instructions are of the form:

```
Operand 3 = Operand 1 <function> Operand 2
```

where Operand 1 is always a Working register (that is, the addressing mode can only be Register Direct), which is referred to as Wb. Operand 2 can be a W register, fetched from data memory, or a 5-bit literal. The result location can be either a W register or a data memory location. The following addressing modes are supported by MCU instructions:

- Register Direct
- Register Indirect
- Register Indirect Post-Modified
- Register Indirect Pre-Modified
- 5-Bit or 10-Bit Literal

> **Note:** Not all instructions support all of the addressing modes given above. Individual instructions can support different subsets of these addressing modes.

REGISTER 7-9: IFS4: INTERRUPT FLAG STATUS REGISTER 4

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	CTMUIF	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	U1EIF	FLTB1IF(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13 **CTMUIF:** CTMU Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12-2 **Unimplemented:** Read as ‘0’

bit 1 **U1EIF:** UART1 Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **FLTB1IF:** PWM1 Fault B Interrupt Flag Status bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

Note 1: This bit is available in dsPIC(16/32)MC102/104 devices only.

8.0 OSCILLATOR CONFIGURATION

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Oscillator (Part VI)"** (DS70644) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

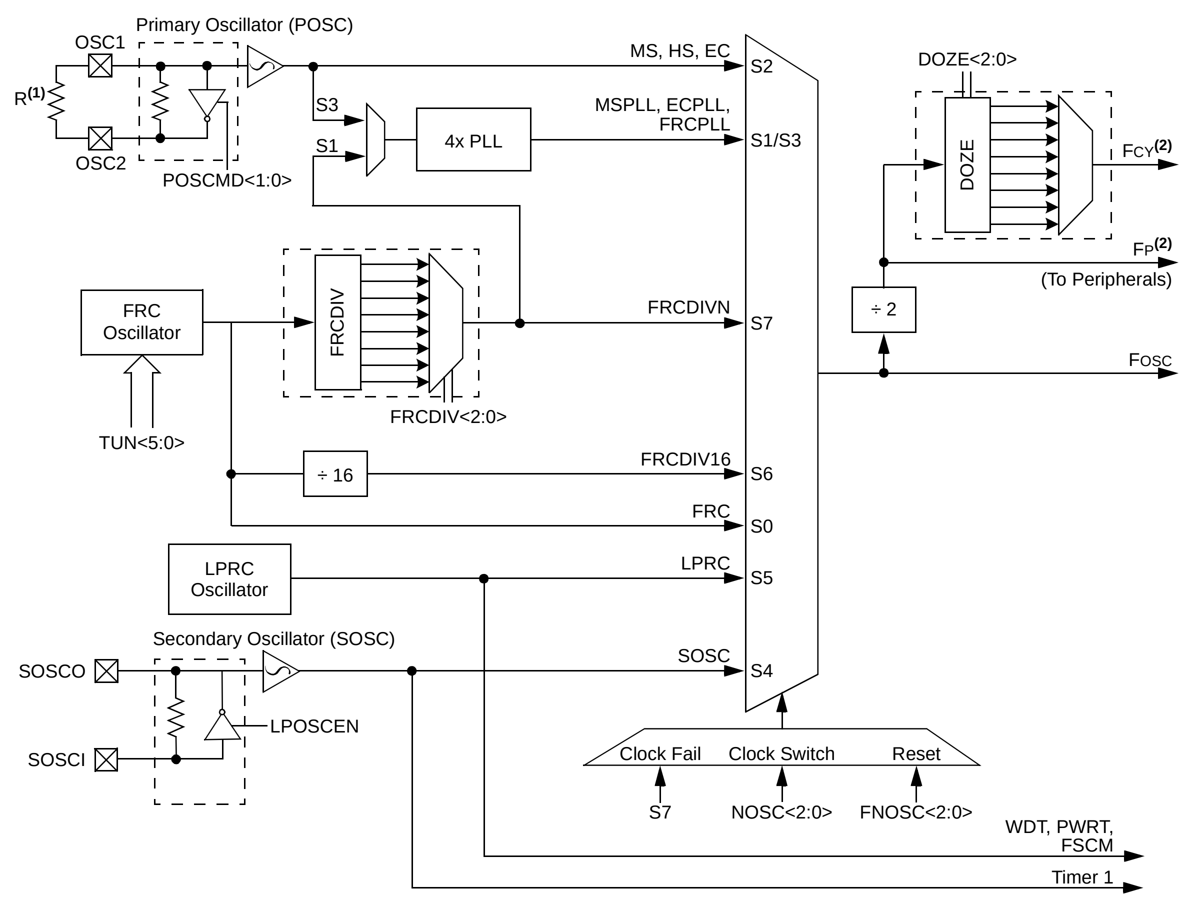
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The oscillator system for dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices provides:

- External and internal oscillator options as clock sources
- An on-chip, 4x Phase Lock Loop (PLL) to scale the internal operating frequency to the required system clock frequency
- An internal FRC oscillator that can also be used with the PLL, thereby allowing full-speed operation without any external clock generation hardware
- Clock switching between various clock sources
- Programmable clock postscaler for system power savings
- A Fail-Safe Clock Monitor (FSCM) that detects clock failure and takes fail-safe measures
- An Oscillator Control register (OSCCON)
- Nonvolatile Configuration bits for main oscillator selection

A simplified diagram of the oscillator system is shown in Figure 8-1.

FIGURE 8-1: OSCILLATOR SYSTEM DIAGRAM



Note 1: If the oscillator is used with MS or HS modes, an extended parallel resistor with the value of 1 MΩ must be connected.

2: The term, FP, refers to the clock source for all peripherals, while FCY refers to the clock source for the CPU. Throughout this document, FCY and FP are used interchangeably, except in the case of Doze mode. FP and FCY will be different when Doze mode is used with a Doze ratio of 1:2 or lower.

10.4.3 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices include three features to prevent alterations to the peripheral map:

- Control register lock sequence
- Continuous state monitoring
- Configuration bit pin select lock

10.4.3.1 Control Register Lock

Under normal operation, writes to the RPINRx and RPORx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK bit (OSCCON<6>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear IOLOCK, a specific command sequence must be executed:

1. Write 0x46 to OSCCON<7:0>.
2. Write 0x57 to OSCCON<7:0>.
3. Clear (or set) IOLOCK as a single operation.

> **Note:** MPLAB® C30 provides built-in C language functions for unlocking the OSCCON register:
>
> ```
> __builtin_write_OSCCONL(value)
> __builtin_write_OSCCONH(value)
> ```
>
> See MPLAB IDE Help for more information.

Unlike the similar sequence with the oscillator's LOCK bit, IOLOCK remains in one state until changed. This allows all of the Peripheral Pin Selects to be configured with a single unlock sequence followed by an update to all control registers, then locked with a second lock sequence.

10.4.3.2 Continuous State Monitoring

In addition to being protected from direct writes, the contents of the RPINRx and RPORx registers are constantly monitored in hardware by shadow registers. If an unexpected change in any of the registers occurs (such as cell disturbances caused by ESD or other external events), a Configuration Mismatch Reset will be triggered.

10.4.3.3 Configuration Bit Pin Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPINRx and RPORx registers. The IOL1WAY (FOSC<5>) Configuration bit blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure will not execute and the Peripheral Pin Select Control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session. Programming IOL1WAY allows user applications unlimited access (with the proper use of the unlock sequence) to the Peripheral Pin Select registers.

REGISTER 10-7: RPINR11: PERIPHERAL PIN SELECT INPUT REGISTER 11

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	OCFAR4	OCFAR3	OCFAR2	OCFAR1	OCFAR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 4-0 **OCFAR<4:0>:** Assign Output Capture A (OCFA) to the Corresponding RPn Pin bits

11111 = Input tied to Vss
11110 = Reserved
.
.
.
11010 = Reserved
11001 = Input tied to RP25
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

NOTES:

12.0 TIMER2/3 AND TIMER4/5

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **“Timers”** (DS70205) in the *“dsPIC33/PIC24 Family Reference Manual”*, which is available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

Timer2/3 and Timer4/5 have three 2-bit timers that can also be configured as two independent 16-bit timers with selectable operating modes.

> **Note 1:** Timer4 and Timer5 are available in dsPIC33FJ32(GP/MC10X) devices only.

As a 32-bit timer, Timer2/3 and Timer4/5 permit operation in three modes:

- Two independent 16-bit timers (e.g., Timer2 and Timer3 or Timer4 and Timer5) with all 16-bit operating modes (except Asynchronous Counter mode)
- Single 32-bit timer (Timer2/3 and Timer4/5)
- Single 32-bit synchronous counter (Timer2/3 and Timer4/5)

Timer2/3 and Timer4/5 also support:

- Timer gate operation
- Selectable prescaler settings
- Timer operation during Idle and Sleep modes
- Interrupt on a 32-bit Period register match
- Time base for input capture and output compare modules (Timer2 and Timer3 only)
- ADC1 event trigger (Timer2/3 only)

Individually, all eight of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed above, except for the event trigger. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, T4CON and T5CON registers (see Register 12-1 through Register 12-4).

For 32-bit timer/counter operation, Timer2/4 is the least significant word (lsw) and Timer3/5 is the most significant word (msw) of the 32-bit timers.

> **Note:** For 32-bit operation, T3CON and T5CON control bits are ignored. Only T2CON and T4CON control bits are used for setup and control. Timer2 and Timer4 clock and gate inputs are used for the 32-bit timer modules, but an interrupt is generated with the Timer3 and Timer5 interrupt flags.

12.1 32-Bit Operation

To configure Timer2/3 and Timer4/5 for 32-bit operation:

1. Set the T32 control bit.
2. Select the prescaler ratio for Timer2 or Timer4 using the TCKPS<1:0> bits.
3. Set the Clock and Gating modes using the corresponding TCS and TGATE bits.
4. Load the timer period value. PR3/PR5 contains the msw of the value, while PR2/PR4 contains the least significant word (lsw).
5. If interrupts are required, set the Timer3 (or Timer5) Interrupt Enable bit, T3IE (or T5IE). Use the priority bits, T3IP<2:0> or T5IP<2:0>, to set the interrupt priority. While Timer2/Timer4 controls the timer, the interrupt appears as a Timer3/Timer5 interrupt.
6. Set the corresponding TON bit.

The timer value at any point is stored in the register pair, TMR3:TMR2 or TMR5:TMR4, which always contains the msw of the count, while TMR2 or TMR4 contains the lsw.

12.2 16-Bit Operation

To configure any of the timers for individual 16-bit operation:

1. Clear the T32 bit corresponding to that timer.
2. Select the timer prescaler ratio using the TCKPS<1:0> bits.
3. Set the Clock and Gating modes using the TCS and TGATE bits.
4. Load the timer period value into the PRx register.
5. If interrupts are required, set the Timerx Interrupt Enable bit, TxIE. Use the priority bits, TxIP<2:0>, to set the interrupt priority.
6. Set the TON bit.

REGISTER 15-8: PxDTCON2: PWMx DEAD-TIME CONTROL REGISTER 2

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	DTS3A	DTS3I	DTS2A	DTS2I	DTS1A	DTS1I
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as ‘0’

bit 5 **DTS3A:** Dead-Time Select for PWM3 Signal Going Active bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 4 **DTS3I:** Dead-Time Select for PWM3 Signal Going Inactive bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 3 **DTS2A:** Dead-Time Select for PWM2 Signal Going Active bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 2 **DTS2I:** Dead-Time Select for PWM2 Signal Going Inactive bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 1 **DTS1A:** Dead-Time Select for PWM1 Signal Going Active bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

bit 0 **DTS1I:** Dead-Time Select for PWM1 Signal Going Inactive bit
1 = Dead time provided from Unit B
0 = Dead time provided from Unit A

REGISTER 20-4: CMxMSKCON: COMPARATOR x MASK GATING CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
HLMS	—	OCEN	OCNEN	OBEN	OBNEN	OAEN	OANEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
NAGS	PAGS	ACEN	ACNEN	ABEN	ABNEN	AAEN	AANEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **HLMS:** High or Low Level Masking Select bits
1 = The masking (blanking) function will prevent any asserted (‘0’) comparator signal from propagating
0 = The masking (blanking) function will prevent any asserted (‘1’) comparator signal from propagating

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **OCEN:** OR Gate C Input Inverted Enable bit
1 = MCI is connected to OR gate
0 = MCI is not connected to OR gate

bit 12 **OCNEN:** OR Gate C Input Inverted Enable bit
1 = Inverted MCI is connected to OR gate
0 = Inverted MCI is not connected to OR gate

bit 11 **OBEN:** OR Gate B Input Inverted Enable bit
1 = MBI is connected to OR gate
0 = MBI is not connected to OR gate

bit 10 **OBNEN:** OR Gate B Input Inverted Enable bit
1 = Inverted MBI is connected to OR gate
0 = Inverted MBI is not connected to OR gate

bit 9 **OAEN:** OR Gate A Input Enable bit
1 = MAI is connected to OR gate
0 = MAI is not connected to OR gate

bit 8 **OANEN:** OR Gate A Input Inverted Enable bit
1 = Inverted MAI is connected to OR gate
0 = Inverted MAI is not connected to OR gate

bit 7 **NAGS:** Negative AND Gate Output Select
1 = Inverted ANDI is connected to OR gate
0 = Inverted ANDI is not connected to OR gate

bit 6 **PAGS:** Positive AND Gate Output Select
1 = ANDI is connected to OR gate
0 = ANDI is not connected to OR gate

bit 5 **ACEN:** AND Gate A1 C Input Inverted Enable bit
1 = MCI is connected to AND gate
0 = MCI is not connected to AND gate

bit 4 **ACNEN:** AND Gate A1 C Input Inverted Enable bit
1 = Inverted MCI is connected to AND gate
0 = Inverted MCI is not connected to AND gate

23.0 SPECIAL FEATURES

> **Note 1:** This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Programming and Diagnostics"** (DS70207) and **"Device Configuration"** (DS70194) in the *"dsPIC33/PIC24 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation

23.1 Configuration Bits

The Configuration Shadow register bits can be configured (read as '0') or left unprogrammed (read as '1') to select various device configurations. These read-only bits are mapped starting at program memory location, 0xF80000. A detailed explanation of the various bit functions is provided in Table 23-4.

Note that address, 0xF80000, is beyond the user program memory space and belongs to the configuration memory space (0x800000-0xFFFFFF), which can only be accessed using Table Reads.

In dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices, the Configuration bytes are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored in the two words at the top of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 23-2. These are packed representations of the actual device Configuration bits, whose actual locations are distributed among several locations in configuration space. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration registers during device Resets.

> **Note:** Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration Word for configuration data. This is to make certain that program code is not stored in this address when the code is compiled.

The upper byte of all Flash Configuration Words in program memory should always be '1111 1111'. This makes them appear to be NOP instructions in the remote event that their locations are ever executed by accident. Since Configuration bits are not implemented in the corresponding locations, writing '1's to these locations has no effect on device operation.

> **Note:** Performing a page erase operation on the last page of program memory clears the Flash Configuration Words, enabling code protection as a result. Therefore, users should avoid performing page erase operations on the last page of program memory.

23.5 In-Circuit Serial Programming™ (ICSP™)

Devices can be serially programmed while in the end application circuit. This is done with two lines for clock and data and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the Digital Signal Controller just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the *"dsPIC33F Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70659) for details about In-Circuit Serial Programming (ICSP).

Any of the three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

23.6 In-Circuit Debugger

When MPLAB® ICD 3 is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB IDE. Debugging functionality is controlled through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{MCLR}$, V_{DD}, V_{SS} and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins.

TABLE 26-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	Symbol	Characteristic[3]	Min	Typ[1]	Max	Units	Conditions
		Program Flash Memory					
D130a	E_P	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	V_{PR}	V_{DD} for Read	V_{MIN}	—	3.6	V	V_{MIN} = Minimum operating voltage
D132b	V_{PEW}	V_{DD} for Self-Timed Write	V_{MIN}	—	3.6	V	V_{MIN} = Minimum operating voltage
D134	T_{RETD}	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	I_{DDP}	Supply Current during Programming	—	10	—	mA	
D137a	T_{PE}	Page Erase Time	20.1	—	26.5	ms	T_{PE} = 168517 FRC cycles, T_A = +85°C, See **Note 2**
D137b	T_{PE}	Page Erase Time	19.5	—	27.3	ms	T_{PE} = 168517 FRC cycles, T_A = +125°C, See **Note 2**
D138a	T_{WW}	Word Write Cycle Time	47.4	—	49.3	µs	T_{WW} = 355 FRC cycles, T_A = +85°C, See **Note 2**
D138b	T_{WW}	Word Write Cycle Time	47.4	—	49.3	µs	T_{WW} = 355 FRC cycles, T_A = +125°C, See **Note 2**

Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.

2: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `b'011111` (for Min), TUN<5:0> = `b'100000` (for Max). This parameter depends on the FRC accuracy (see Table 26-18) and the value of the FRC Oscillator Tuning register (see Register 8-3). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 “Programming Operations”**.

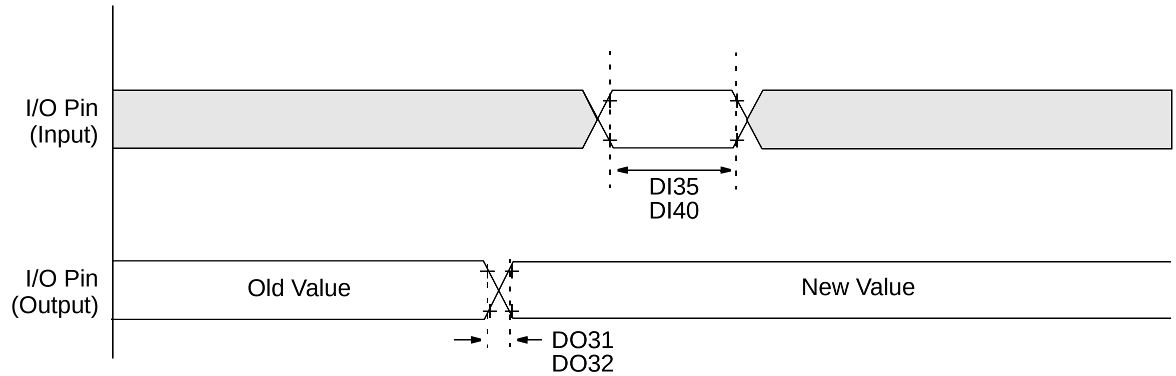
3: These parameters are ensured by design, but are not characterized or tested in manufacturing.

TABLE 26-13: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +125°C for Extended				
Param No.	Symbol	Characteristics	Min	Typ	Max	Units	Comments
—	C_{EFC}	External Filter Capacitor Value[1]	4.7	10	—	µF	Capacitor must be low series resistance (< 5 ohms)

Note 1: Typical V_{CAP} voltage = 2.5V when $V_{DD} \geq V_{DDMIN}$.

FIGURE 26-3: CLKO AND I/O TIMING CHARACTERISTICS



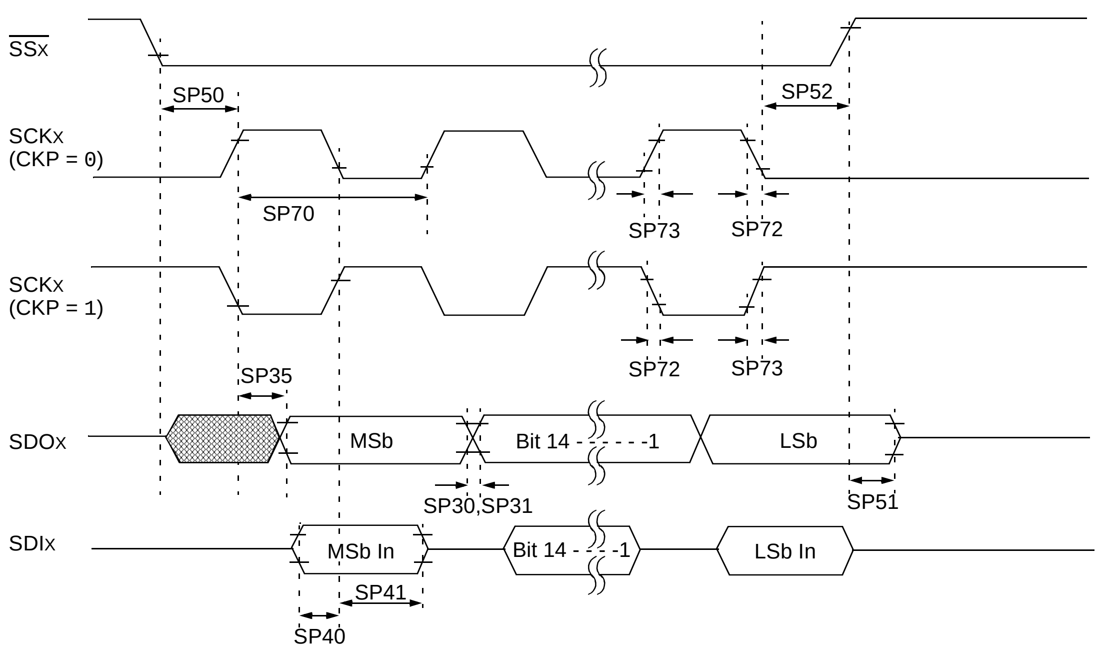
Note: Refer to Figure 26-1 for load conditions.

TABLE 26-20: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Symbol**	**Characteristic(2)**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	10	25	ns	
DO32	TIOF	Port Output Fall Time	—	10	25	ns	
DI35	TINP	INTx Pin High or Low Time (input)	25	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

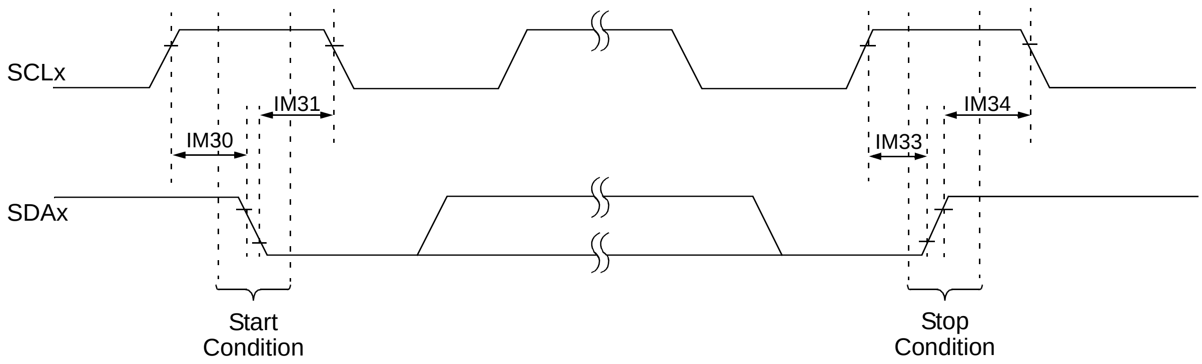
Note 1: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.
2: These parameters are characterized, but are not tested in manufacturing.

FIGURE 26-26: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING CHARACTERISTICS FOR dsPIC33FJ32(GP/MC)10X



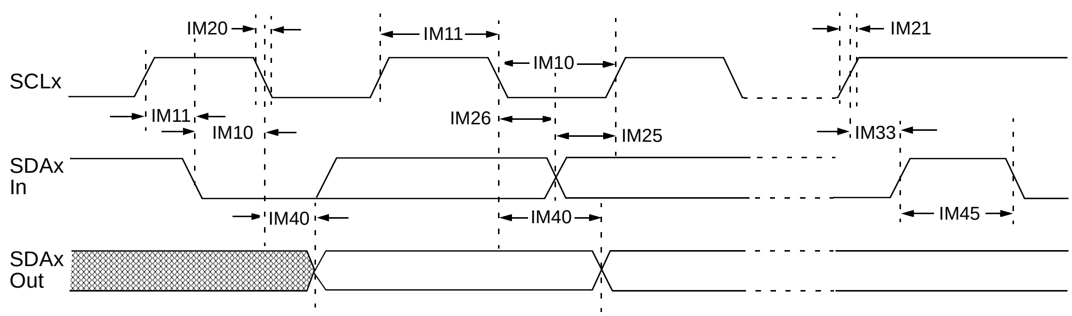
Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-27: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)



Note: Refer to Figure 26-1 for load conditions.

FIGURE 26-28: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)

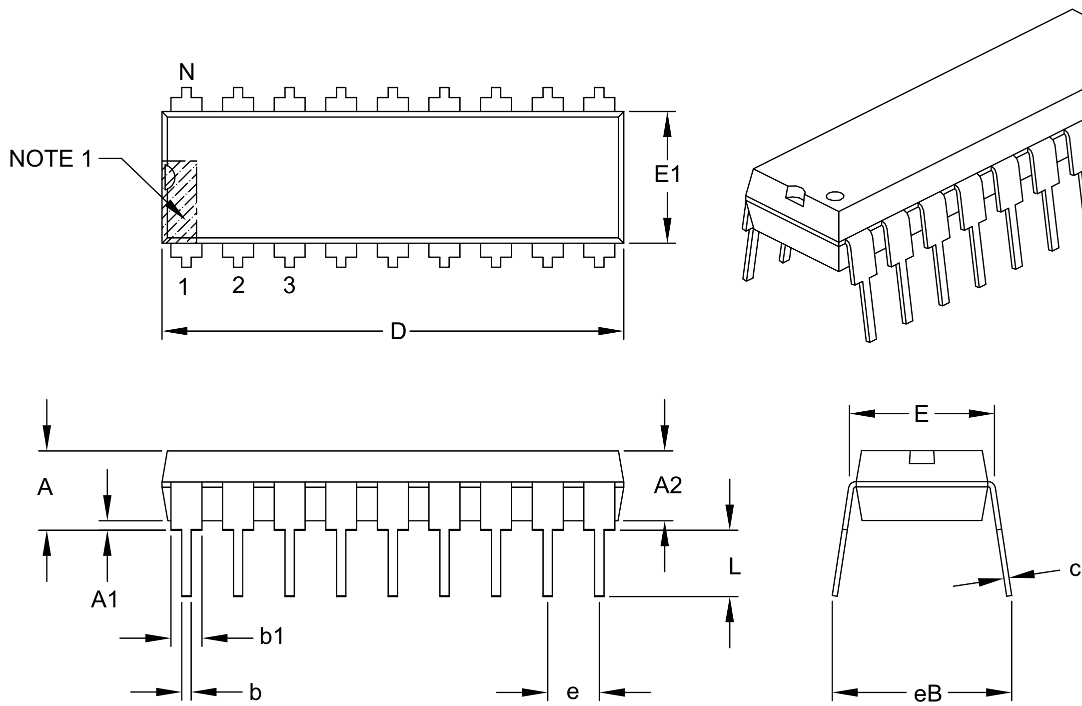


Note: Refer to Figure 26-1 for load conditions.

28.2 Package Details

18-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		18	
Pitch	e		.100 BSC	
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.880	.900	.920
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.014
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

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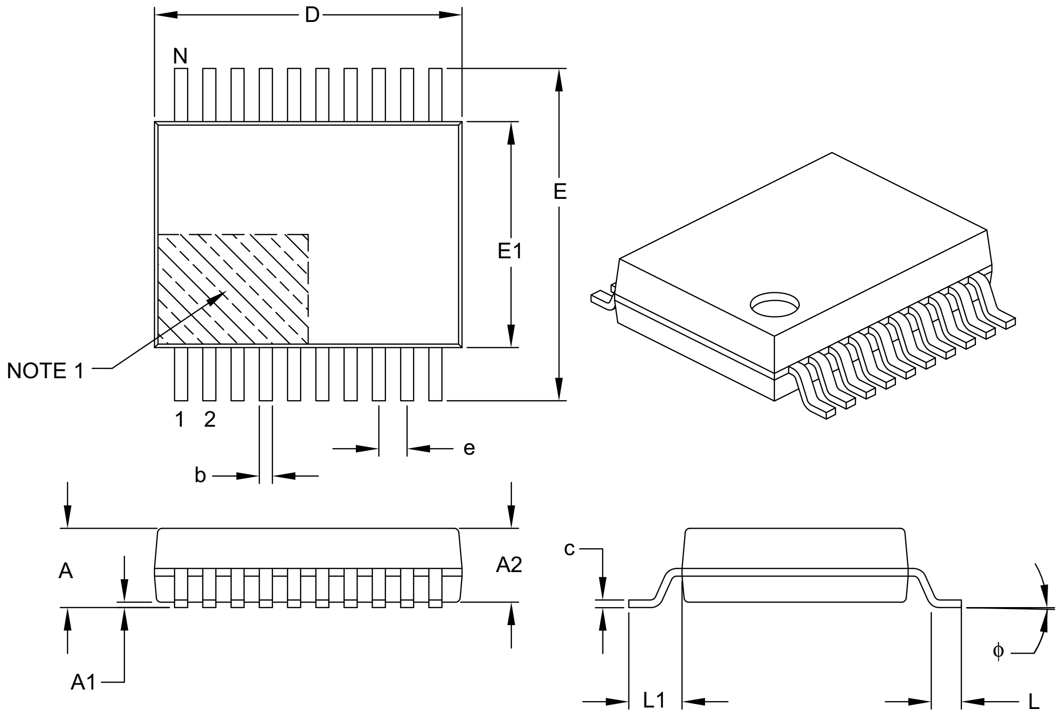
20-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Pins	N	20		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	6.90	7.20	7.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-072B

NOTES:

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